

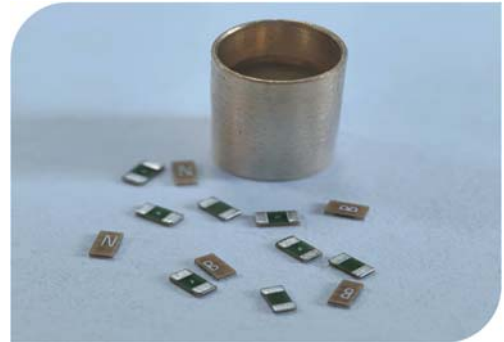
Ultra-Thin Fuse | 0.06x0.03"

0603TD-L Series

Time Delay series Thin Film Chip Fuse

Features:

- Low DCR
- High inrush current withstanding capability
- High reliability
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating layer
- Halogen free, RoHS compliance & lead-free



Application:

- Panel
- HDD
- Toy
- IoT
- Battery pack
- Finger print
- Smart lock
- Notebook

Electrical Characteristics

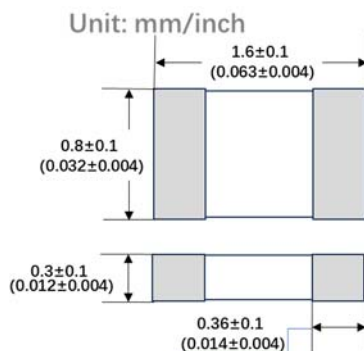
% of Current Rating	Opening Time
100%	4hours min.
200%	5second max.
300%	0.2second max.

Specifications

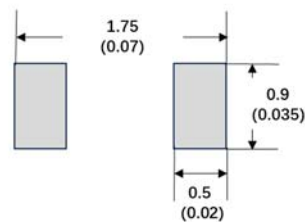
Part No.	Current Rating(A)	Voltage Rating (Vdc)	Interrupting Rating	Typical Cold DCR (Ω)	Typical I^2t (A^2Sec)*	Marking
0603TD-R750-L	0.75	35	35A @35V	0.11	0.02	H

*Typical I^2t : i.e. melting I^2t at 0.001s of current rating

Dimension



Pad layout



Packaging

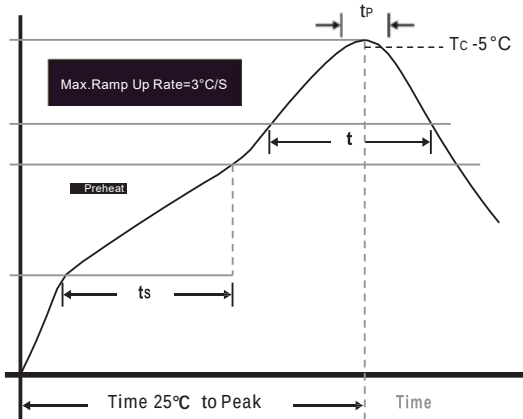
- Quantity: 5, 000pcs
- 8mm wide tape on 178mm (7 inch) diameter reel -specification EIA Standard 481

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Soldering Parameters



IR Reflow Profile

Preheat

Temperature min (T _{min})	150°C
Temperature max (T _{max})	200°C
Time (T _{min} to T _{max}) (t _s)	60 – 120 seconds
Average ramp up rate (T _{max} to T _p)	3°C/second max

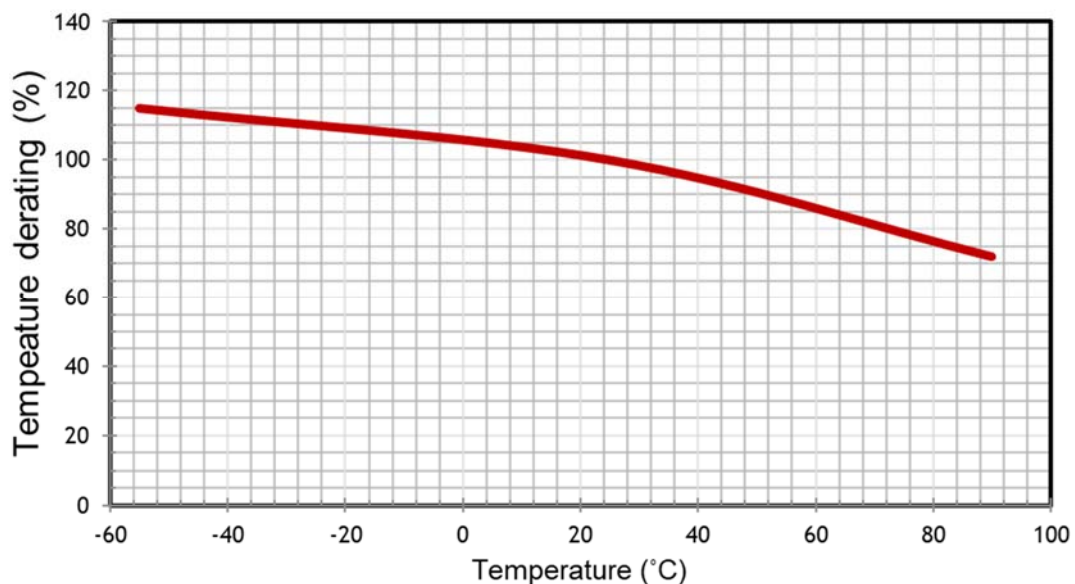
Reflow

Liquidous temperature (T _L)	217°C
Time at liquidous (t _L)	60 – 150 seconds
Peak temperature (T _p)	260°C
Time within 5°C of actual peak Temperature (t _p)	30 seconds*
Average ramp-down rate (T _p to T _{max})	6°C/second max
Time 25°C to peak temperature	8 minutes Max.

Wave Soldering: 260°C, 10 seconds max.

Infrared Reflow: 260°C, 30 seconds max.

Temperature Effect on Current Rating



- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 105°C

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Average Time-Current curve

